

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 05-129662

(43)Date of publication of application : 25.05.1993

(51)Int.Cl.

H01L 33/00

(21)Application number : 03-313463

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(22)Date of filing : 31.10.1991

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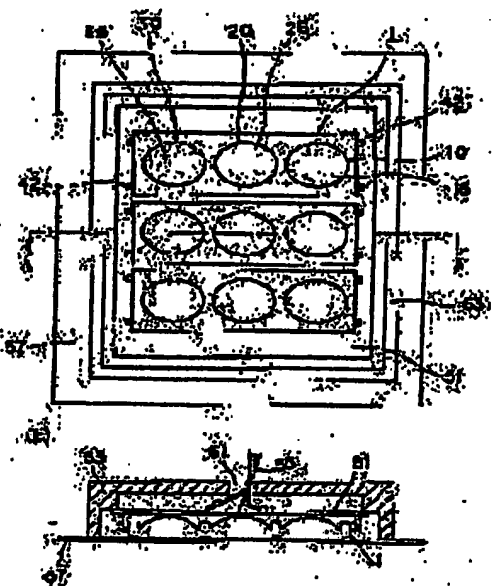
SUZUKI SHINYA

(54) MANUFACTURE OF LIGHT EMISSION DIODE LAMP

(57)Abstract

PURPOSE: To improve workability during resin sealing of a reflection type light emission diode.

CONSTITUTION: Arrays of three light emission diodes each are arranged in three lines on a board 51 and stored into a lamp case 53. The front face of the lamp case 53 containing radiation faces 16, 26, 36 of light emission diodes 10, 20, 30 of a light emission diode array 1 is covered with a heat-resistant adhesive tape 57 with no clearances. With the front face of the lamp case 53 turned down, a black epoxy resin is injected from the rear side of the lamp case 53 to defoam in a vacuum. After the light emission diode arrays 1 and the board 51 are pervaded full with the resin, it is cured in a dry furnace at about 80° C; finally, the adhesive tape 57 is peeled off.



LEGAL STATUS

[Date of request for examination] 29.09.1998

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than withdrawal the examiner's decision of rejection or application converted registration]

[Date of final disposal for application] 17.05.2000

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]